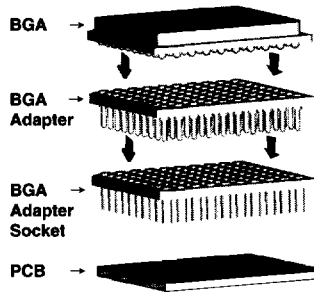
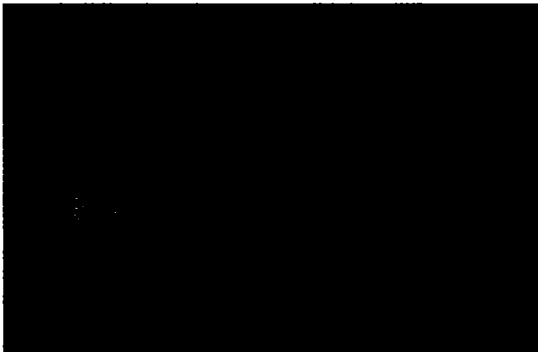
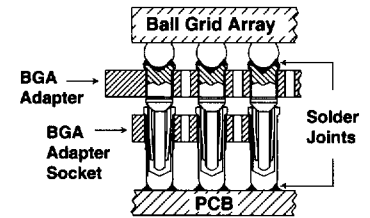


## BGA Adapters



Before Soldering



After Soldering

### Features:

- Soldering BGA to adapter subjects BGA to less thermal stress than soldering BGA to a mother board due to the adapters lower mass.
- Countersink in head of pin allows easy positioning of BGA onto adapter.
- Head above insulator in adapter allows visual inspection for solder shorts in both X & Y axis.
- Custom adapters available for heat sink attachment.
- Extraction slot for tool #5082-2 shown on page 163.

### Terminals:

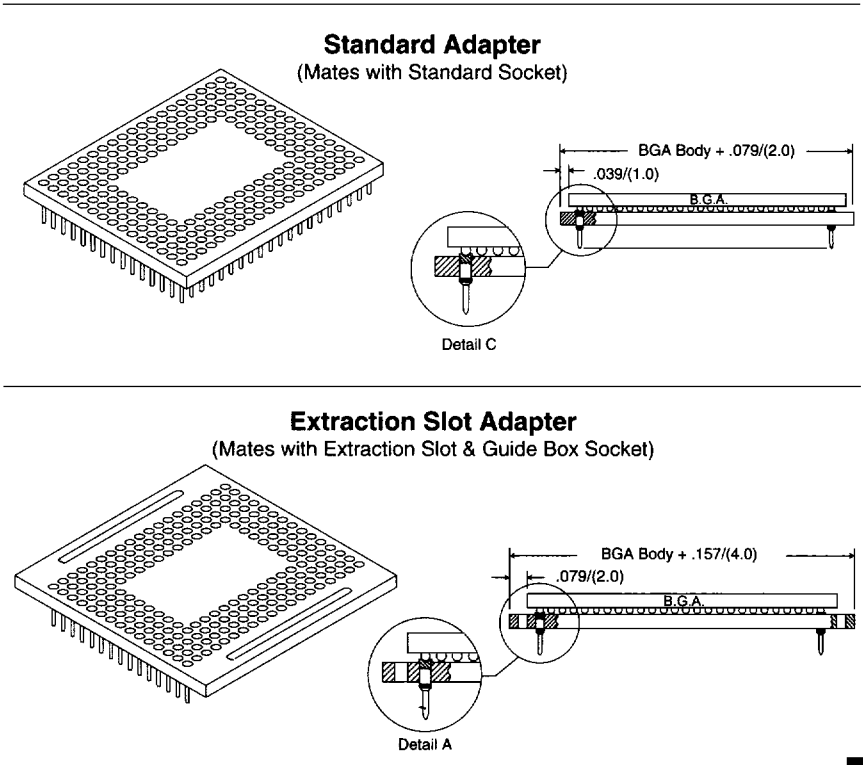
Brass - Copper Alloy 360, ASTM-B-16

### Plating:

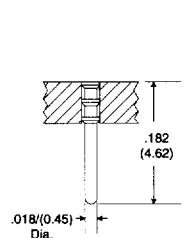
Terminal TL: Tin Lead over Nickel  
Terminal G: Gold over Nickel

### Body Material:

FR-4 Glass Epoxy, U.L. Rated 94V-0

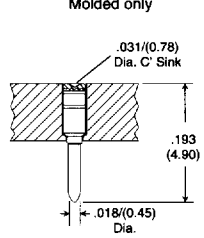


Type -638



### Terminals

Type -647  
Molded only



### How To Order

